19-4140; Rev 4; 8/10

## 2MHz, High-Brightness LED Drivers with Integrated MOSFET and High-Side Current Sense

## **General Description**

The MAX16832A/MAX16832C step-down constant-current high-brightness LED (HB LED) drivers provide a cost-effective design solution for automotive interior/exterior lighting, architectural and ambient lighting, LED bulbs, and other LED illumination applications.

The MAX16832A/MAX16832C operate from a +6.5V to +65V input voltage range and can provide an output current up to 700mA, if operated up to a temperature of +125°C, or up to a 1A if operated up to a temperature of +105°C. A high-side current-sense resistor adjusts the output current, and a dedicated pulse-width modulation (PWM) input enables pulsed LED dimming over a wide range of brightness levels.

These devices are well suited for applications requiring a wide input voltage range. The high-side current sensing and an integrated current-setting circuitry minimize the number of external components while delivering an average output current with  $\pm 3\%$  accuracy. A hysteretic control method ensures excellent input supply rejection and fast response during load transients and PWM dimming. The MAX16832A allows 10% current ripple, and the MAX16832C allows 30% current ripple. Both devices operate up to a 2MHz switching frequency, thus allowing the use of small-sized components.

The MAX16832A/MAX16832C offer an analog dimming feature that reduces the output current by applying an external DC voltage below the internal 2V threshold voltage from TEMP\_I to GND. TEMP\_I also sources 25µA to a negative temperature coefficient (NTC) thermistor connected between TEMP\_I and GND, thus providing an analog thermal-foldback feature that reduces the LED current when the temperature of the LED string exceeds a specified temperature point. Additional features include thermal-shutdown protection.

The MAX16832A/MAX16832C operate over the -40°C to +125°C automotive temperature range and are available in a thermally enhanced 8-pin SO package.

## **Applications**

Architectural, Industrial, and Ambient Lighting Automotive RCL, DRL, and Fog Lights Heads-Up Displays Indicator and Emergency Lighting MR16 and MR111 LED Lights

Pin Configuration appears at end of data sheet.

## **Features**

X16832A/MAX16832C

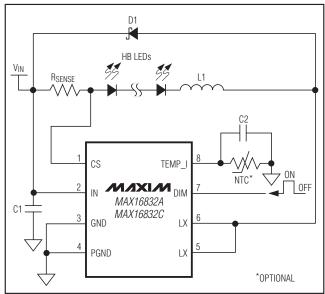
- ♦ High-Efficiency Solution
- ♦ 6.5V to 65V Input Voltage Range
- Output Current Up to 1A
- On-Board 65V, 0.45Ω Power MOSFET
- Hysteretic Control: Up to 2MHz Switching Frequency
- ♦ ±3% LED Current Accuracy
- ♦ 200mV Current-Sense Reference
- Resistor-Programmable Constant LED Current
- Integrated High-Side Current Sense
- Thermal-Foldback Protection/Linear Dimming
- Thermal-Shutdown Protection
- Available in a Thermally Enhanced 8-Pin SO Package
- ♦ -40°C to +125°C Operating Temperature Range

## Ordering Information

PART	TEMP RANGE	PIN-PACKAGE		
MAX16832AASA+	-40°C to +125°C	8 SO-EP*		
MAX16832CASA+	-40°C to +125°C	8 SO-EP*		

+Denotes a lead(Pb)-free/RoHS-compliant package. \*EP = Exposed pad.

## \_Typical Application Circuit



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For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

#### **ABSOLUTE MAXIMUM RATINGS**

IN, CS, LX, DIM to GND	
TEMP_I to GND	0.3V to +6V
PGND to GND	0.3V to +0.3V
CS to IN	0.3V to +0.3V
Maximum Current into Any Pin	
(except IN, LX, and PGND)	20mA
Continuous Power Dissipation ( $T_A = +7$	70°C)
8-Pin SO (derate 23.3mW/°C above	+70°C)1860.5mW
Junction-to-Ambient Thermal Resistance	e (θJA) (Note 1)43°C/W

Operating Temperature Range	
700mA (max) Output Current	40°C to +125°C
1A (max) Output Current	40°C to +105°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Soldering (reflow)	+260°C
Lead Temperature (soldering, 10s)	+300°C
Pin-to-Pin ESD Ratings	

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Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a fourlayer board. For detailed information on package thermal considerations, refer to <u>www.maxim-ic.com/thermal-tutorial</u>.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

## **ELECTRICAL CHARACTERISTICS**

 $(V_{IN} = +24V, V_{DIM} = V_{IN}, T_A = T_J = -40^{\circ}C$  to  $+125^{\circ}C$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Input Voltage Range	VIN		6.5		65	V
Ground Current		No switching		1.5		mA
Supply Current		$V_{DIM} < 0.6V, V_{IN} = 12V$		350		μΑ
UNDERVOLTAGE LOCKOUT (UV	LO)					
Undervoltage Lockout	UVLO	$V_{CS}$ = $V_{IN}$ - 100mV, $V_{IN}$ rising until $V_{LX}$ < $0.5 V_{IN}$		6.25	6.5	- V
		$V_{CS}$ = $V_{IN}$ - 100mV, $V_{IN}$ falling until $V_{LX}$ > $0.5V_{IN}$			6.0	
Undervoltage-Lockout Hysteresis				0.5		V
SENSE COMPARATOR						
		MAX16832A, V <sub>IN</sub> - V <sub>CS</sub> rising from 140mV until V <sub>LX</sub> > 0.5V <sub>IN</sub> , V <sub>DIM</sub> = 5V	201	210	216	mV
Sense Voltage Threshold High	Vsnshi	$\label{eq:MAX16832C, V_{IN} - V_{CS} rising from 140mV} \\ until V_{LX} > 0.5V_{IN}, V_{DIM} = 5V \\ \end{tabular}$	218	230	236	
	V <sub>SNSLO</sub>	MAX16832A, V <sub>IN</sub> - V <sub>CS</sub> falling from 260mV until V <sub>LX</sub> < 0.5V <sub>IN</sub> , V <sub>DIM</sub> = 5V	185	190	198	- mV
Sense Voltage Threshold Low		MAX16832C, V <sub>IN</sub> - V <sub>CS</sub> falling from 260mV until V <sub>LX</sub> < 0.5V <sub>IN</sub> , V <sub>DIM</sub> = 5V	166	170	180	
Propagation Delay to Output High	t <sub>DPDH</sub>	Falling edge of V_{IN} - V_{CS} from 140mV to 260mV to V_{LX} > 0.5V_{IN}		50		ns
Propagation Delay to Output Low	t <sub>DPDL</sub>	Rising edge of V <sub>CS</sub> - V <sub>IN</sub> from 260mV to 140mV to V <sub>LX</sub> < 0.5V <sub>IN</sub>		50		ns
CS Input Current	ICSIN	$V_{IN}$ - $V_{CS}$ = 200mV, $V_{IN}$ = $V_{CS}$			3.5	μΑ
INTERNAL MOSFET						
Drain-to-Source Resistance	Rdson	$\label{eq:VIN} \begin{array}{l} V_{IN} = V_{DIM} = 24V, \ V_{CS} = 23.9V, \\ I_{LX} = 700mA \end{array}$		0.45	0.9	Ω
		$\label{eq:VIN} \begin{array}{l} V_{IN} = V_{DIM} = 6.0V, \ V_{CS} = 5.9V, \\ I_{LX} = 700mA \end{array}$		1	2	52
LX Leakage Current	ILX_LEAK	$V_{\text{DIM}} = 0V, V_{\text{LX}} = 65V$			10	μA

2

## **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{IN} = +24V, V_{DIM} = V_{IN}, T_A = T_J = -40^{\circ}C$  to  $+125^{\circ}C$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}C$ .)

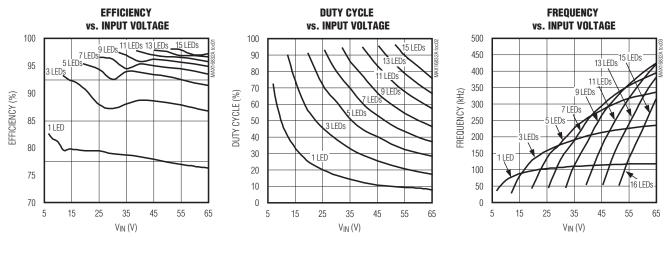
PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	МАХ	UNITS
DIM INPUT						
DIM Input-Voltage High	VIH	$V_{IN} - V_{CS} = 100 \text{mV}$	2.8			V
DIM Input-Voltage Low	VIL	$V_{CS} - V_{IN} = 100 \text{mV}$			0.6	V
DIM Turn-On Time	t <sub>DIM_ON</sub>	$V_{DIM}$ rising edge to $V_{LX} < 0.5 V_{IN}$		200		ns
DIM Input Leakage High		$V_{\text{DIM}} = V_{\text{IN}}$		8	15	μA
DIM Input Leakage Low		$V_{\text{DIM}} = 0V$	-3	-1.5	0	μA
THERMAL SHUTDOWN						
Thermal-Shutdown Threshold		Temperature rising	+165		°C	
Thermal-Shutdown Threshold Hysteresis			10		°C	
THERMAL FOLDBACK						
Thermal-Foldback Enable V <sub>TFB_ON</sub>		V <sub>DIM</sub> = 5V	1.9	2.0	2.12	V
Thermal-Foldback Slope	FBSLOPE	V <sub>DIM</sub> = 5V		0.75		1/V
TEMP_I Output Bias Current	ITEMP_I		25	26.5	28	μA

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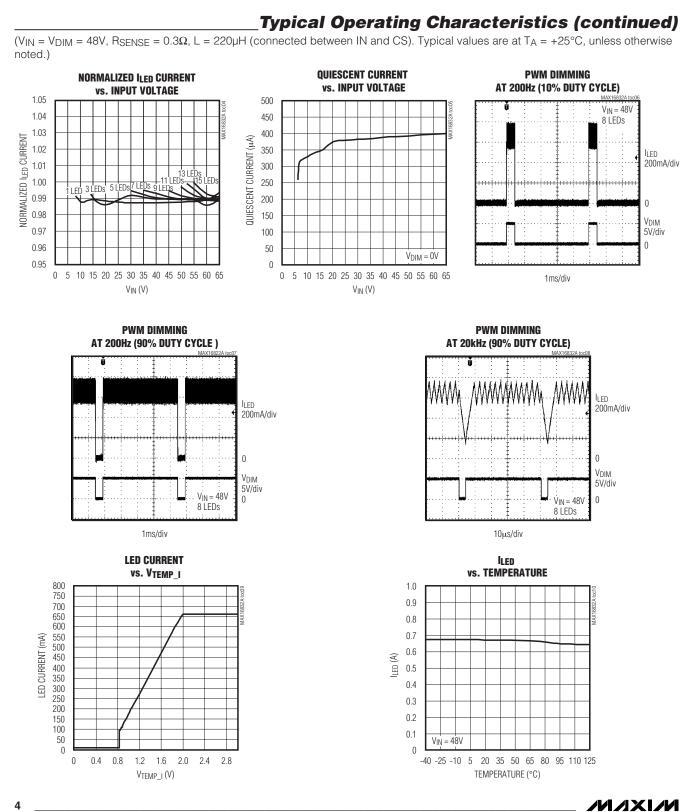
MAX16832A/MAX16832C

## **Typical Operating Characteristics**

 $(V_{IN} = V_{DIM} = 48V, R_{SENSE} = 0.3\Omega, L = 220\mu$ H (connected between IN and CS). Typical values are at T<sub>A</sub> = +25°C, unless otherwise noted.)



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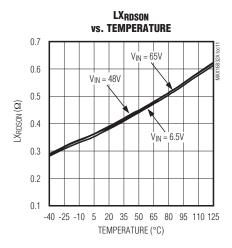


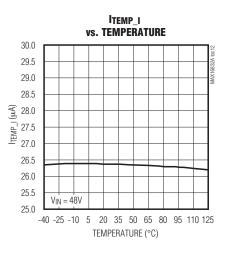
MAX16832A/MAX16832C

Downloaded from Elcodis.com electronic components distributor

## **Typical Operating Characteristics (continued)**

 $(V_{IN} = V_{DIM} = 48V, R_{SENSE} = 0.3\Omega, L = 220\mu H$  (connected between IN and CS). Typical values are at T<sub>A</sub> = +25°C, unless otherwise noted.)





## **Pin Description**

PIN	NAME	FUNCTION
1	CS	Current-Sense Input. Connect a resistor between IN and CS to program the LED current.
2	IN	Positive Supply Voltage Input. Bypass with a 1µF or higher value capacitor to GND.
3	GND	Ground
4	PGND	Power Ground
5, 6	LX	Switching Node
7	DIM	Logic-Level Dimming Input. Drive DIM low to turn off the current regulator. Drive DIM high to enable the current regulator.
8	TEMP_I	Thermal Foldback Control and Linear Dimming Input. Bypass with a 0.01µF capacitor to GND if thermal foldback or analog dimming is used. See the <i>Thermal Foldback</i> section.
_	EP	Exposed Pad. Connect EP to a large-area ground plane for effective power dissipation. Do not use as the IC ground connection.

## **Detailed Description**

The MAX16832A/MAX16832C are step-down, constantcurrent, HB LED drivers. These devices operate from a +6.5V to +65V input voltage range. The maximum output is 1A, if the part is used at temperatures up to  $T_A$  = +105°C, or 700mA, if it is used up to  $T_A$  = +125°C. A high-side current-sense resistor sets the output current and a dedicated PWM dimming input enables pulsed LED dimming over a wide range of brightness levels.

A high-side current-sensing scheme and an on-board current-setting circuitry minimize the number of external components while delivering LED current with  $\pm$ 3% accuracy, using a 1% sense resistor. See Figure 1 for a functional diagram.



5

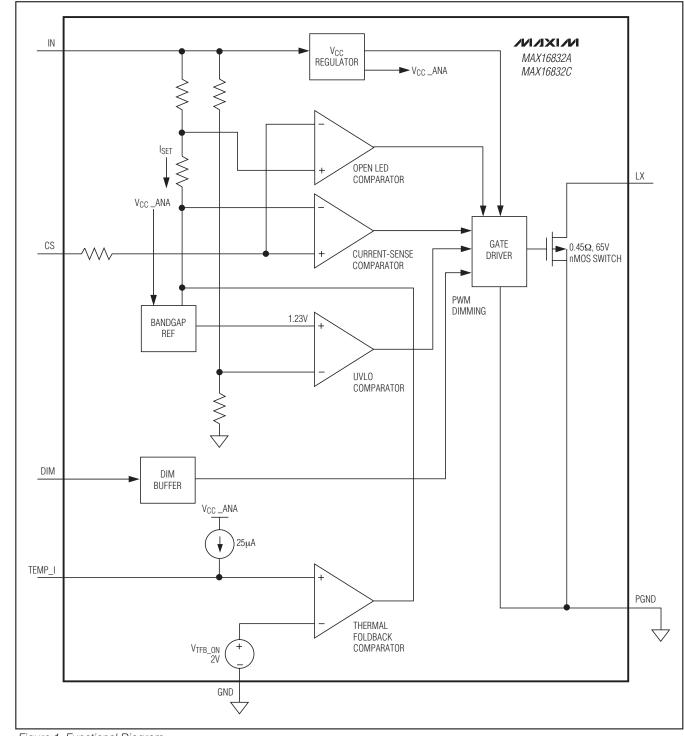


Figure 1. Functional Diagram

MAX16832A/MAX16832C

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#### **Undervoltage Lockout (UVLO)**

The MAX16832A/MAX16832C include a UVLO with 500mV hysteresis. The internal MOSFET turns off when  $V_{\rm IN}$  falls below 5.5V to 6.0V.

#### **DIM Input**

LED dimming is achieved by applying a PWM signal at DIM. A logic level below 0.6V at DIM forces the MAX16832A/MAX16832Cs' output low, thus turning off the LED current. To turn the LED current on, the logic level at DIM must be greater than 2.8V.

#### **Thermal Shutdown**

The MAX16832A/MAX16832C thermal-shutdown feature turns off the LX driver when the junction temperature exceeds +165°C. The LX driver turns back on when the junction temperature drops 10°C below the shutdown temperature threshold.

**Analog Dimming** The MAX16832A/MAX16832C offer an analog-dimming feature that reduces the output current when the voltage at TEMP\_I is below the internal 2V threshold voltage. The MAX16832A/MAX16832C achieve analog dimming by either an external DC voltage source connected between TEMP\_I and ground or by a voltage on a resistor connected across TEMP\_I and ground induced by an internal current source of 25µA. When the voltage at TEMP\_I is below the internal 2V threshold limit, the MAX16832A/MAX16832C reduce the LED current. Use the following formula to set the analog dimming current:

$$I_{TF}(A) = I_{LED}(A) \times \left[1 - FB_{SLOPE}\left(\frac{1}{V}\right) \times \left(V_{TFB_{ON}} - V_{AD}\right)(V)\right]$$

where  $V_{TFB_ON} = 2V$  and  $FB_{SLOPE} = 0.75$  are obtained from the *Electrical Characteristics* table and  $V_{AD}$  is the voltage at TEMP\_I.

#### Thermal Foldback

The MAX16832A/MAX16832C include a thermal-foldback feature that reduces the output current when the temperature of the LED string exceeds a specified temperature point. These devices enter thermal-foldback mode when the voltage drop on the NTC thermistor, thermally attached to the LEDs and electrically connected between TEMP\_I and ground, drops below the internal 2V threshold limit.

## \_\_Applications Information

#### Selecting RSENSE to Set LED Current

The LED current is programmed with a current-sense resistor connected between IN and CS. Use the following equation to calculate the value of this resistor:

$$R_{\text{SENSE}}(\Omega) = \frac{1}{2} \frac{(V_{\text{SNSHI}} + V_{\text{SNSLO}})(V)}{I_{\text{LED}}(A)}$$

where V<sub>SNSHI</sub> is the sense voltage threshold high and V<sub>SNSLO</sub> is the sense voltage threshold low (see the *Electrical Characteristics* table for values).

#### **Current-Regulator Operation**

The MAX16832A/MAX16832C regulate the LED current using a comparator with hysteresis (see Figure 2). As the current through the inductor ramps up and the voltage across the sense resistor reaches the upper threshold, the internal MOSFET turns off. The internal MOSFET turns on again when the inductor current ramps down through the freewheeling diode until the voltage across the sense resistor equals the lower threshold. Use the following equation to determine the operating frequency:

$$f_{SW} = \frac{(V_{IN} - nV_{LED}) \times nV_{LED} \times R_{SENSE}}{V_{IN} \times \Delta V \times L}$$

where n is the number of LEDs, V<sub>LED</sub> is the forward voltage drop of 1 LED, and  $\Delta V = (V_{SNSHI} - V_{SNSLO})$ .

#### **Inductor Selection**

The MAX16832A/MAX16832C operate up to a switching frequency of 2MHz. For space-sensitive applications, the high switching frequency allows the size of the inductor to be reduced. Use the following formula to calculate an approximate inductor value and use the closest standard value:

$$L(approx.) = \frac{(V_{IN} - nV_{LED}) \times nV_{LED} \times R_{SENSE}}{V_{IN} \times \Delta V \times f_{SW}}$$

For component selection, use the MAX16832A/C Design Tool available at: <u>www.maxim-ic.com/MAX16832-</u> <u>software</u>.



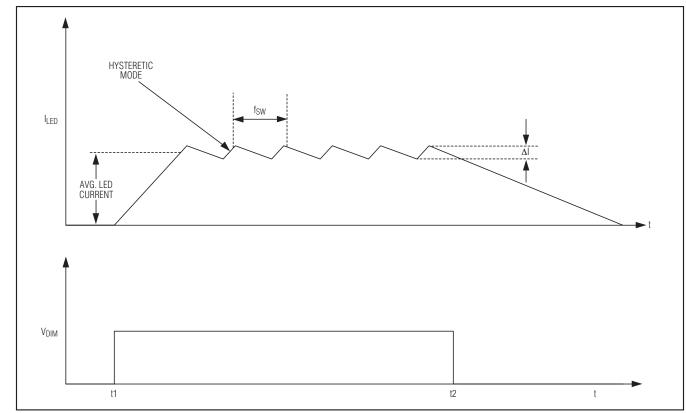


Figure 2. Current-Regulator Operation

#### **Freewheeling-Diode Selection**

For stability and best efficiency, a low forward-voltage drop diode with fast reverse-recovery time and low capacitance is recommended. A Schottky diode is a good choice as long as its breakdown voltage is high enough to withstand the maximum operating voltage.

#### **PCB Layout Guidelines**

Careful PCB layout is critical to achieve low switching losses and stable operation. In normal operation, there are two power loops. One is formed when the internal MOSFET is on and the high current flows from ground through the input cap, RSENSE, the LED load, the inductor, and the internal MOSFET back to ground. The second loop is formed when the internal MOSFET is off and the high current circulates from the input cap positive terminal through RSENSE, the LED load, the inductor, and the freewheeling diode and back to the input cap positive terminal. Note that the current through RSENSE, the LED load, and the inductor is basically DC with some triangular ripple (low noise). The high-noise, large signal, fast transition switching currents only flow through the freewheeling diode to the input cap positive

terminal, or through the MOSFET to ground and then to the input cap positive terminal. Without a proper PCB layout, these square-wave switching currents can create problems in a hysteretic LED driver.

The current control depends solely on the voltage across RSENSE. Any noise pickup on this node induces erratic switching of the internal MOSFET (the IC will operate at a much higher frequency). To help prevent this, place RSENSE as close as possible to CS and IN and keep the sense traces short. It is especially important to keep the square-wave switching currents in the freewheeling diode away from RSENSE. To minimize interference, place the freewheeling diode on the opposite side of the IC as RSENSE and position the input capacitor near the diode so it can return the high frequency currents to ground. The layout in Figure 3 should be used as a guideline. The dashed line shows the path of the high frequency components that cause disruption in operation. For a good thermal design, the exposed pad on the IC should solder to a large pad with many vias to the backside ground plane.

8

MAX16832A/MAX16832C

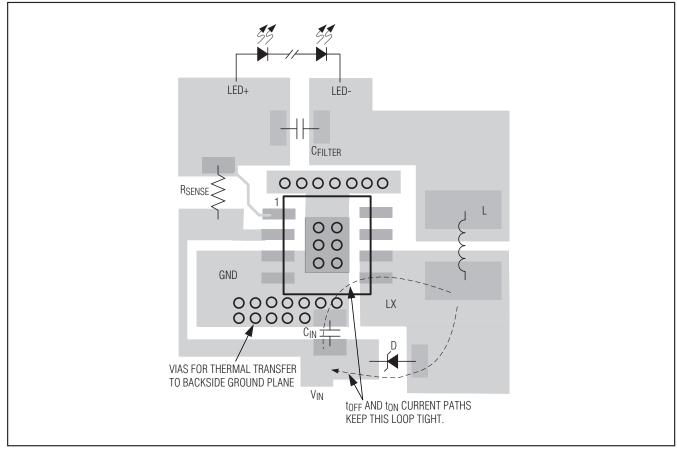
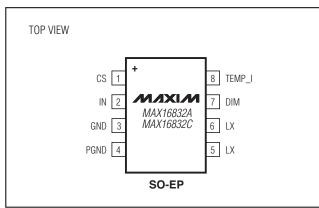


Figure 3. PCB Layout





## Chip Information

PROCESS: BICMOS

## **Package Information**

For the latest package outline information and land patterns, go to **www.maxim-ic.com/packages**. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE	PACKAGE	OUTLINE NO.	LAND
TYPE	CODE		PATTERN NO.
8 SO-EP	S8E-12	<u>21-0111</u>	<u>90-0150</u>

MAX16832A/MAX16832C

## **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	5/08	Initial release	—
1	9/08	Introduced the MAX16832C	1
2	5/09	Revised General Description, Features, Absolute Maximum Ratings, and Detailed Description	1, 2, 5
3	2/10	Updated PCB Layout Guidelines and added Figure 3	8, 9
4	8/10	Corrected Functional Diagram and added Soldering (reflow) to Absolute Maximum Ratings	2, 5, 6

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10

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